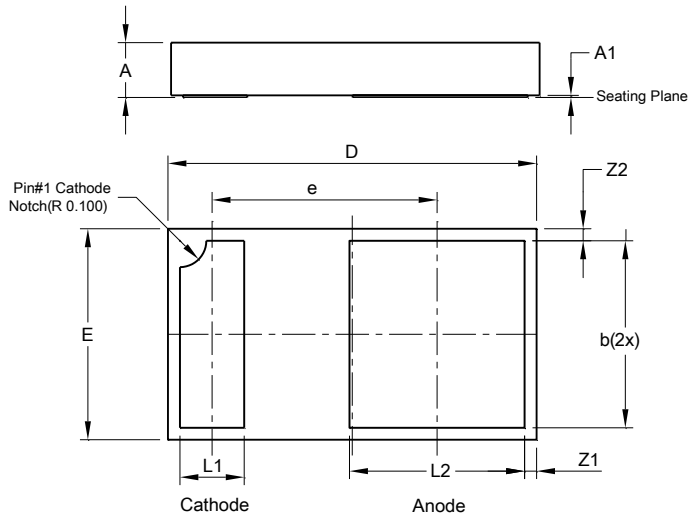


Package Outline Dimensions

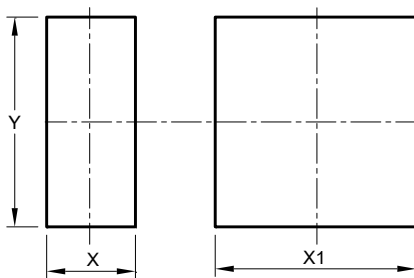
X4-WLCUS1408-2



X4-WLCUS1408-2			
Dim	Min	Max	Typ
A	0.17	0.25	0.20
A1	0.006	0.01	0.008
b	0.659	0.759	0.709
D	1.35	1.45	1.40
E	0.75	0.85	0.80
e	-	-	0.855
L1	0.194	0.294	0.244
L2	0.615	0.715	0.665
Z1	0.016	0.076	0.046
Z2	0.016	0.076	0.046
All Dimensions in mm			

Suggested Pad Layout

X4-WLCUS1408-2



Dimensions	Value (in mm)
X	0.334
X1	0.755
X2	1.386
Y	0.789

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.